



5650 HR

Semi-automatic Heavy Ribbon- Wedge-Bonder

The semi-automatic Wedge-Wedge Bonder 5650HR fills the gap between the manual Wedge-Bonders series 54xx to the automatic bonder.

On basis of the 5600-series the bonder is fully PC controlled and allows any number of bonds to be programmed.

Pre-programmed adjust points are targeted through the camera's cross hair targeting system and the programmed bonds are executed automatically.

Two operating modes are available: Single bond for repair of various samples in order to perform a single bond.(manual-automatic) Multi wire for teaching and bonding of single chips or various samples (semi and fully automatic).

The 5650 can also be used as a Au Wire or AL Thin Wire Bonder as well as pull-/shear tester by simply replacing the bond head and loading the appropriate software.

change over time: approx. 3 minutes.
Ask us for more information !

Specifications

Mechanics

X, Y table

Working area 100 x 115 mm
Resolution 0,25 µm, repeatability < 2 µm

Z-axis

60 mm

Speed

up to ≤20 wires/min.

Bond head

Wedge-Wedge Alu- Heavy Ribbon

Axis of rotation ± 360°

90° quick-change wire guide and cutter

Bondforce programmable up to 3500cN

increased mechanical Bondforce

Ultrasonic system

57 KHz

Ribbon size

from 500µm X 75µm up to 2000µm X 300µm

Copper wire from 300...500µm

Loop Forms

Triangular, rectangular, reverse, stitch bond programmable

Controls

Computer

Single-Board PC, 600 MHz Pentium processor,
256 MB RAM, Ethernet, USB 4x + 4x frontside

Monitor

TFT flat screen

Operation system

Windows 7

Printer

All Windows-compatible printers can be installed

All bonding parameters can be printed

Work holder

2x2" standard with mechanical clamping
4x4" optional, as well with vacuum

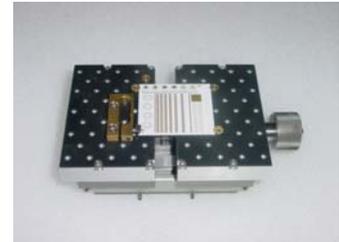
Other features

Programming: Automatic bonding of hybrids, power modules or others with programmable X/Y table

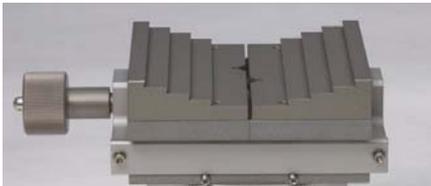
Work holders



For components up to 4 x 4"
Vacuum and mechanical clamping



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Customised work holders are available on request.

Head Parking System For storing of temporary not required bondheads (5610/30/32/50) or pull- and shear-heads. Can be mounted on the left or right side of the machine

General

Camera With cross hair targeting for positioning of bonds

Microscope Stereoskop Standard 40x, other

Microscopes optional

Lighting 20 W halogen spot light, optional LED direct light

Incident light optional, ringlight, spotlight

programmable

Dimensions Height 70 cm, width 70 cm, depth 65 cm; approx. 70

kg

Supplies 100...240 VAC, single-phase, 50/60 Hz, max.500VA

Connections Air 6 bar, vacuum - 0,7 bar \varnothing 6 mm

Optional **DLC DeformationLimitControl**

PRU Structuresearch

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